ABSTRACT

A composition capable of providing excellent bonding characteristics, including bond strength, even at relatively high temperatures and even without the use of styrene as a reactive diluent, comprising polymerizable vinyl ester compounds, preferably in combination with a select reactive diluent for the polymerizable vinyl ester compounds, wherein the polymerizable vinyl ester compounds are preferably present in the adhesive compositions in amounts of from about 10 wt% to about 30 wt%.